KR DMLN31.23 specified at 65mA

SYNIOS® P2720

This compact LED device is part of the SYNIOS P2720 family. Given the scalability of this product family, it provides full performance and flexibility with just one footprint. The KR DMLN31.23 product is meant to provide superior light quality in ¼ mm² chip size class. The higher robustness and standard-ized footprint makes the LED flexible for any RGBW application.



Applications

- Architecture / Garden Lighting (LED & Laser)
- Interior Illumination (e.g. Ambient Map)
- Signalling
- Transportation, Plane, Ship

Features:

- Package: SMD epoxy package
- Chip technology: Thinfilm
- Typ. Radiation: 120° (Lambertian emitter)
- Color: $\lambda_{dom} = 621 \text{ nm} (\bullet \text{ red})$
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified with RV-level 1
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)







Ordering Information

Туре	Luminous Flux ¹⁾ I _F = 65 mA Φ _V	Ordering Code
KR DMLN31.23-6E5G-25-F3T3	8.0 20.1 lm	Q65112A3414



Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
	1	max.	125 °C
Storage Temperature	T _{stg}	min.	-40 °C
		max.	125 °C
Junction Temperature	T _j	max.	150 °C
Junction Temperature for short time applications*	T _j	max.	175 °C
Forward current	I _F	min.	5 mA
T _s = 25 °C		max.	250 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T _s = 25 °C	Ι _{FS}	max.	1000 mA
Reverse voltage ²⁾ T _s = 25 °C	V _R	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

* The median lifetime (L70/B50) for Tj = 175° C is 100h.



Characteristics

 $I_{_{\rm F}}$ = 65 mA; $T_{_{
m S}}$ = 25 °C

Parameter	Symbol		Values
Dominant Wavelength ³⁾ I _F = 65 mA	λ_{dom}	min. typ. max.	612 nm 621 nm 627 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	18 nm
Viewing angle at 50% $\rm I_{\rm v}$	2φ	typ.	120 °
Forward Voltage ⁴⁾ I _F = 65 mA	V_{F}	min. max.	1.85 V 2.60 V
Reverse current ²⁾ $V_R = 12 V$	۱ _R	typ. max.	0.01 μA 10 μA
Real thermal resistance junction/solderpoint ⁵⁾	$R_{thJS real}$	typ. max.	17 K / W 23 K / W
Electrical thermal resistance junction/solderpoint $^{\rm 5)}$ with efficiency $\eta_{\rm e}$ = 40 %	$R_{thJS elec.}$	typ. max.	10 K / W 14 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ I _F = 65 mA min. Φ _V	Luminous Flux ¹⁾ I _F = 65 mA max. Φ _v	Luminous Intensity ⁶⁾ I _F = 65 mA typ. I _v	
6E	8.0 lm	9.0 lm	2.8 cd	
7E	9.0 lm	10.0 lm	3.1 cd	
8E	10.0 lm	11.2 lm	3.5 cd	
5F	11.2 lm	12.5 lm	3.9 cd	
6F	12.5 lm	14.0 lm	4.4 cd	
7F	14.0 lm	15.9 lm	4.9 cd	
8F	15.9 lm	18.0 lm	5.6 cd	
5G	18.0 lm	20.1 lm	6.3 cd	

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ I _F = 65 mA min. V _F	Forward Voltage ⁴⁾ I _F = 65 mA max. V _F	
F3	1.85 V	2.00 V	
J3	2.00 V	2.15 V	
M3	2.15 V	2.30 V	
Q3	2.30 V	2.45 V	
Т3	2.45 V	2.60 V	

Wavelength Groups

Group	Dominant Wavelength ³⁾ $I_F = 65 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ³⁾ I _F = 65 mA max. λ _{dom}
2	612 nm	616 nm
3	616 nm	620 nm
4	620 nm	624 nm
5	624 nm	627 nm



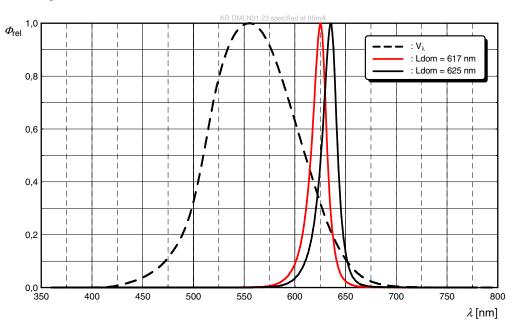
Group Name on Label

Example: 5F-2-F3 Brightness	Wavelength	Forward Voltage
5F	2	F3



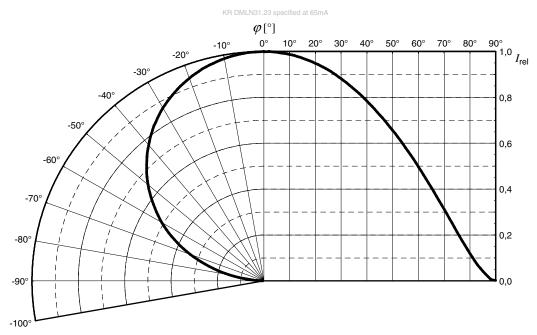
Relative Spectral Emission⁶⁾

 $\Phi_{_{rel}}$ = f (λ); I $_{_F}$ = 65 mA; T $_{_S}$ = 25 °C



Radiation Characteristics⁶⁾

 $I_{rel} = f(\phi); T_{s} = 25 \ ^{\circ}C$





50

5 1,7 1,8

2,0

2,2

2,4

2,6

 $V_{\mathsf{F}}\left[\mathsf{V}\right]$

Forward current ^{6), 7)} Relative Luminous Flux ^{6), 7)} $\Phi_{v}/\Phi_{v}(65 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$ $I_{_{\rm F}} = f(V_{_{\rm F}}); T_{_{\rm S}} = 25 \ ^{\circ}{\rm C}$ Φ_V Φ_V(65*mA*) 3,5 *I*_F [mA] ²⁵⁰ : Ldom = 617 nm Ldom = 617 nm : Ldom = 625 nm : Ldom = 625 nm 3,0 200 2,5 150 2,0 1,5 100 1,0

0,5

0,0 ^لے م

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, 6⁰

200

49⁰

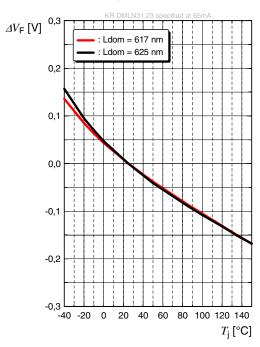
I_F [mA]

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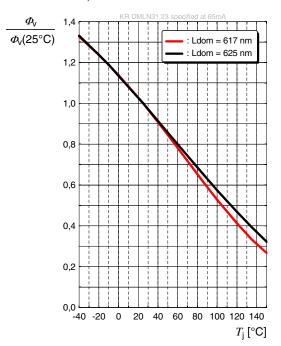
Forward Voltage ⁶⁾

 $\Delta V_{_F} = V_{_F} - V_{_F}(25 \text{ °C}) = f(T_{_j}); I_{_F} = 65 \text{ mA}$



Relative Luminous Flux⁶⁾

 $\Phi_v/\Phi_v(25 \ ^{\circ}C) = f(T_i); I_F = 65 \ mA$

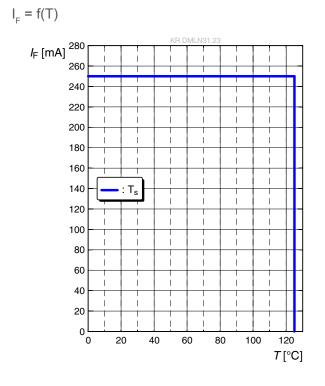


Dominant Wavelength⁶⁾

 $\Delta \lambda_{dom} = \lambda_{dom} - \lambda_{dom} (25 \ ^{\circ}C) = f(T_j); I_F = 65 \text{ mA}$ $\Delta \lambda_{dom} [nm] \xrightarrow{10} \underbrace{KR DMLN31.23 \text{ specified at 65mA}}_{5} \underbrace{Ldom = 617 \text{ nm}}_{5} \underbrace{Ldom = 625 \text{ nm}}_{5} \underbrace{1000}_{-10} \underbrace{1000}_{-1000}_{-10} \underbrace{1000}_{-10} \underbrace{10$

*T*_j [°C]

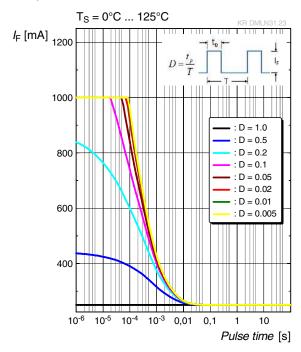




Max. Permissible Forward Current

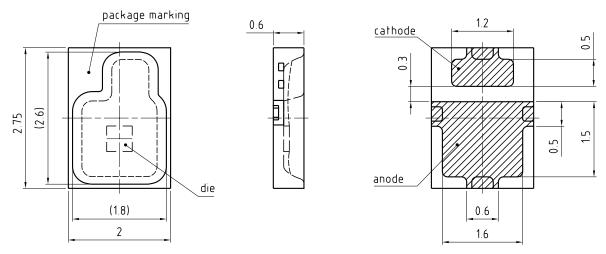
Permissible Pulse Handling Capability

 $I_{_{P}} = f(t_{_{P}}); D: Duty cycle$





Dimensional Drawing⁸⁾



General tolerance ±0.1	
Lead finish Au	

Further Information:

Approximate Weight: 12.0 mg

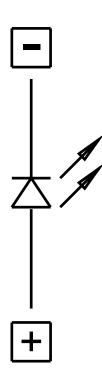
Corrosion test:

Class: 3B Test condition: 40°C / 90 % RH / 15 ppm $\rm H_2S$ / 14 days (stricter than IEC 60068-2-43)

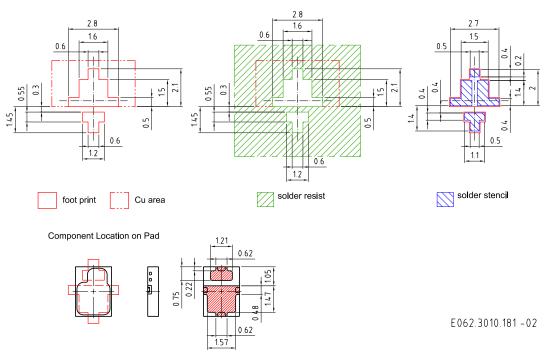


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Electrical Internal Circuit



Recommended Solder Pad⁸⁾

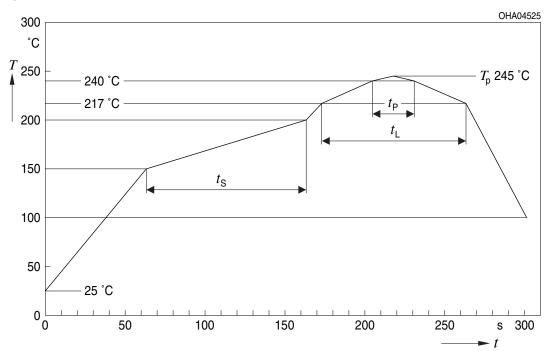


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



Profile Feature	Symbol Pb-Free (SnAgCu) Assembly			Unit	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t _s T _{smin} to T _{smax}	t _s	60	100	120	S
Ramp-up rate to peak ^{*)} T_{smax} to T_{p}			2	3	K/s
Liquidus temperature	TL		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	Τ _Ρ		245	260	°C
Time within 5 °C of the specified peak temperature T_p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

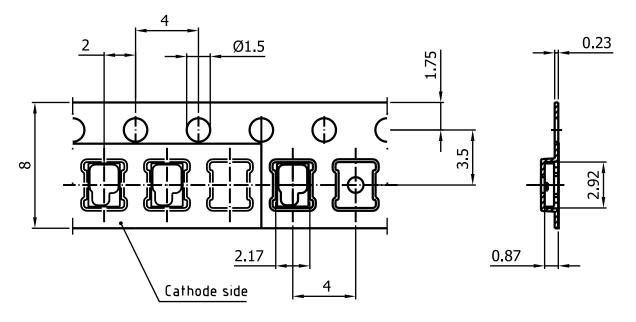
All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



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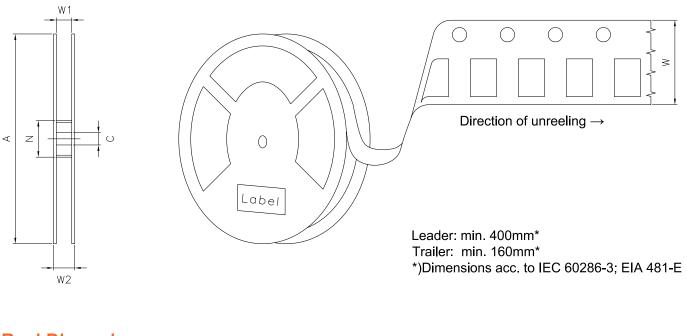




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Tape and Reel ⁹⁾

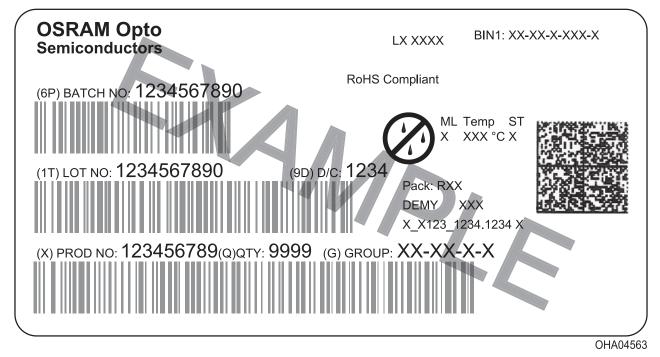


Reel Dimensions

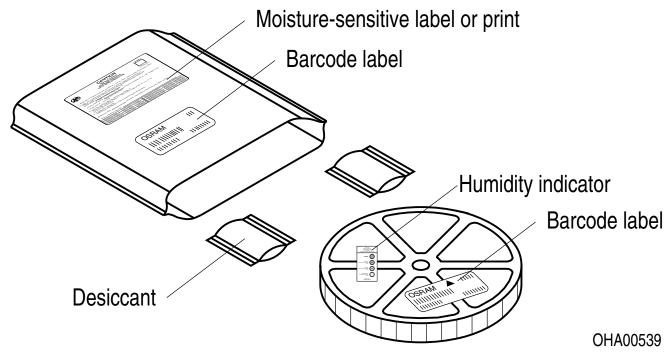
А	W	N _{min}	W ₁	$W_{2 \max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials⁸⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

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Glossary

- ¹⁾ **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 8 % and an expanded uncertainty of ± 11 % (acc. to GUM with a coverage factor of k = 3).
- ²⁾ **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- ³⁾ **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- ⁴⁾ **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of k = 3).
- ⁵⁾ **Thermal Resistance:** Rth max is based on statistic values (6σ).
- ⁶⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁷⁾ **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- ⁸⁾ **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁹⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



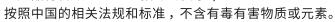
Revision History				
Version	Date	Change		
1.1	2021-02-18	Features Schematic Transportation Box Dimensions of Transportation Box Glossary		



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